MBRS230L, NRVBS230L

Surface Mount **Schottky Power Rectifier**

SMB Power Surface Mount Package

This device employs the Schottky Barrier principle in a metal-to-silicon power rectifier. Features epitaxial construction with oxide passivation and metal overlay contact. Ideally suited for low voltage, high frequency switching power supplies; free wheeling diodes and polarity protection diodes.

Features

- Compact Package with J–Bend Leads Ideal for Automated Handling
- Highly Stable Oxide Passivated Junction
- Guardring for Over-Voltage Protection
- Low Forward Voltage Drop
- NRVBS Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q101 Qualified and PPAP Capable*
- These Devices are Pb-Free and are RoHS Compliant

Mechanical Characteristics

- Case: Molded Epoxy
- Epoxy Meets UL 94, V-0 @ 0.125 in.
- Weight: 95 mg (approximately)
- Finish: All External Surfaces Corrosion Resistant and Terminal Leads are Readily Solderable
- Maximum Temperature of 260°C/10 Seconds for Soldering
- Available in 12 mm Tape, 2500 Units per 13" Reel, Add "T3" Suffix to Part Number
- Cathode Polarity Band



ON Semiconductor®

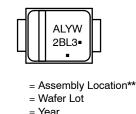
www.onsemi.com

SCHOTTKY BARRIER RECTIFIER 2.0 AMPERES **30 VOLTS**



SMB CASE 403A

MARKING DIAGRAM



Α L

Y

W

= Work Week = Pb-Free Package

(Note: Microdot may be in either location)

**The Assembly Location code (A) is front side optional. In cases where the Assembly Location is stamped in the package bottom (molding ejecter pin), the front side assembly code may be blank.

ORDERING INFORMATION

Device	Package	Shipping [†]
MBRS230LT3G	SMB (Pb-Free)	2500 / Tape & Reel
NRVBS230LT3G*	SMB (Pb-Free)	2500 / Tape & Reel

+For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

MBRS230L, NRVBS230L

MAXIMUM RATINGS

Rating	Symbol	Value	Unit
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage	V _{RRM} V _{RWM} V _R	30	V
Average Rectified Forward Current (At Rated V_R , $T_C = 110^{\circ}$ C)	IO	2.0	A
Peak Repetitive Forward Current (At Rated V _R , Square Wave, 20 kHz, T_C = 105°C)	I _{FRM}	4.0	A
Non-Repetitive Peak Surge Current (Surge Applied at Rated Load Conditions, Halfwave, Single Phase, 60 Hz)	I _{FSM}	40	A
Storage/Operating Case Temperature	T _{stg} , T _C	-55 to +175	°C
Operating Junction Temperature	TJ	-55 to +125	°C
Voltage Rate of Change (Rated V_R , $T_J = 25^{\circ}$ C)	dv/dt	10,000	V/µs

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

THERMAL CHARACTERISTICS

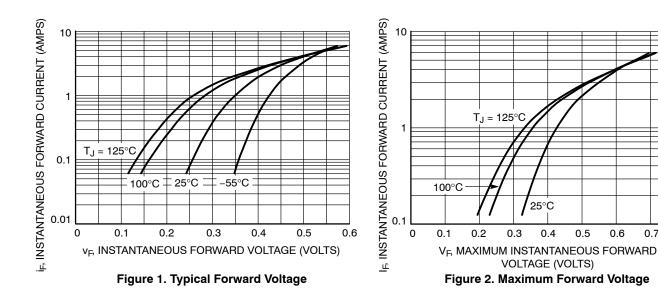
Characteristic	Symbol	Value	Unit
Thermal Resistance,			°C/W
Junction-to-Lead (Note 1)	$R_{\theta JL}$	18.6	
Thermal Resistance, Junction-to-Ambient (Note 1)	$R_{\theta JA}$	135	
	• • 0 JA		

ELECTRICAL CHARACTERISTICS

Maximum Instantaneous Forward Voltage (Note 2)		V _F	T _J = 25°C	T _J = 125°C	
	(I _F = 2.0 A) (I _F = 4.0 A)		0.50	0.45	V
see Figure 2	(I _F = 4.0 A)		0.60	0.63	
Maximum Instantaneous Reverse Current (Note 2)			T _J = 25°C	T _J = 125°C	
	(V _R = 30 V)	I _R	1	75	mA

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions. 1. Minimum pad size (0.108" X 0.085") for each lead on FR4 board.

2. Pulse Test: Pulse Width \leq 250 µs, Duty Cycle \leq 2.0%.

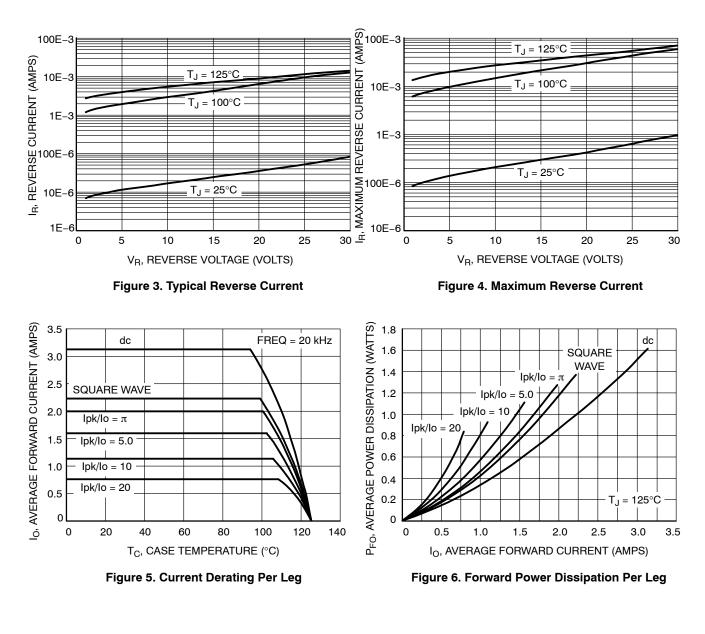


0.6

0.7

0.8

MBRS230L, NRVBS230L



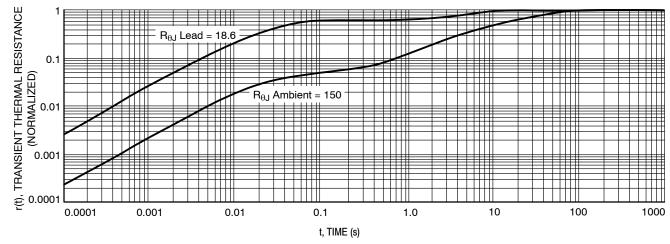
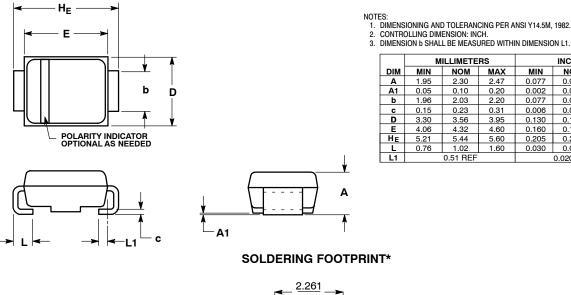


Figure 7. Thermal Response

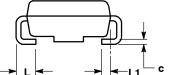
PACKAGE DIMENSIONS

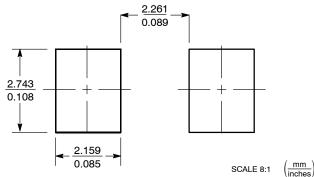
SMB CASE 403A-03 **ISSUE J**



CONTROLLING DIMENSION: INCH DIMENSION b SHALL BE MEASURED WITHIN DIMENSION L1.

	MILLIMETERS			INCHES		
DIM	MIN	NOM	MAX	MIN	NOM	MAX
Α	1.95	2.30	2.47	0.077	0.091	0.097
A1	0.05	0.10	0.20	0.002	0.004	0.008
b	1.96	2.03	2.20	0.077	0.080	0.087
c	0.15	0.23	0.31	0.006	0.009	0.012
D	3.30	3.56	3.95	0.130	0.140	0.156
Е	4.06	4.32	4.60	0.160	0.170	0.181
HE	5.21	5.44	5.60	0.205	0.214	0.220
Г	0.76	1.02	1.60	0.030	0.040	0.063
L1	0.51 REF			0.020 REF		





*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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